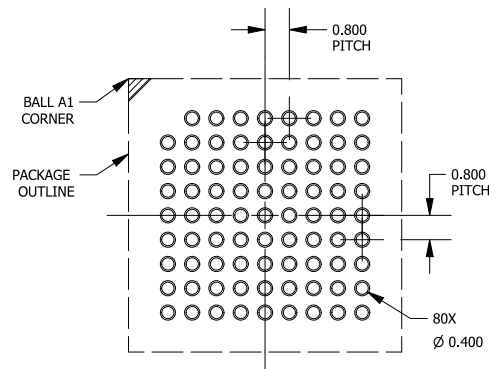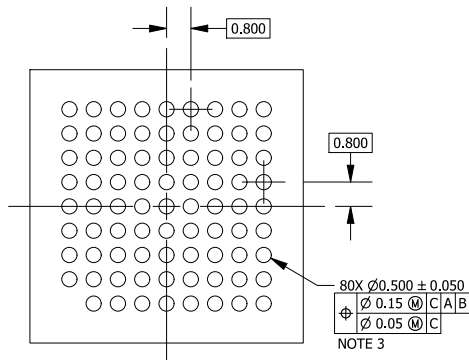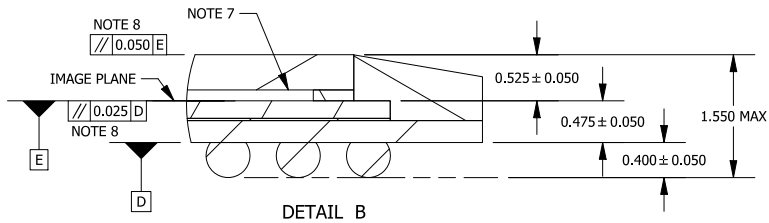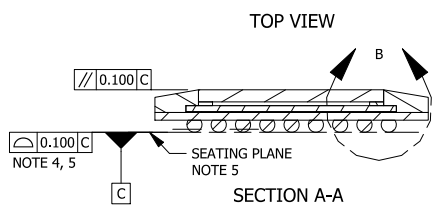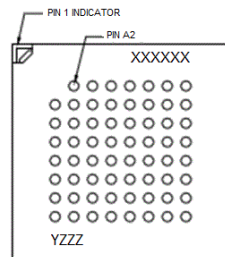**IBGA80 9x9**
CASE 503CB
ISSUE A

DATE 05 FEB 2020
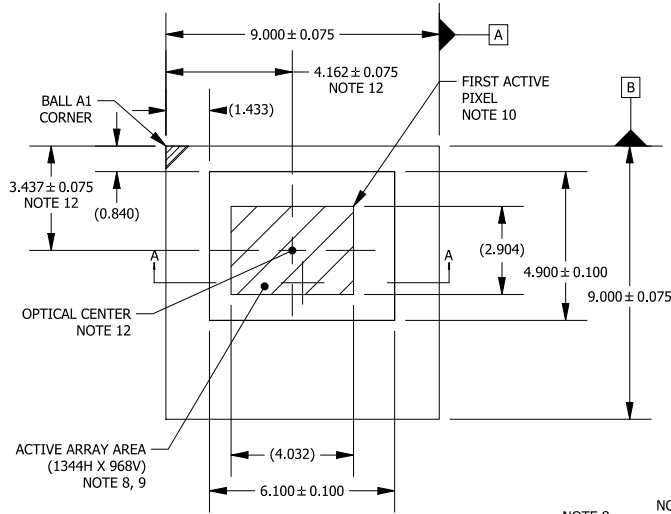
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R <1% 420-850nm (EACH SIDE).
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ± 0.5°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.338, 1.063).

TOP VIEW

SECTION A-A

DETAIL B

BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE
STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD
THE ON SEMICONDUCTOR SOLDERING AND MOUNTING
TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
Y   = Year
ZZZ   = Lot Traceability

*This information is generic. Please refer to
device data sheet for actual part marking.
Pb–Free indicator, "G" or microdot "▪", may
or may not be present. Some products may
not follow the Generic Marking.

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